

www.ti.com

SLTS261C -MAY 2006-REVISED SEPTEMBER 2009

100-W 48-V INPUT ISOLATED DC/DC CONVERTER

Check for Samples: PTQA430025, PTQA430033, PTQA420050

FEATURES

- 100-W Output
- Input Voltage Range: 36 V to 75 V
- 92% Efficiency
- 1500 Vdc Isolation
- Fast Transient Response
- On/Off Control
- Overcurrent Protection
- Differential Remote Sense
- Adjustable Output Voltage
- Output Overvoltage Protection
- Over-Temperature Shutdown
- Undervoltage Lockout
- Standard 1/4-Brick Footprint
- UL Safety Agency Approval



DESCRIPTION

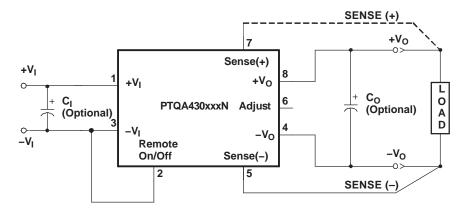
The PTQA series of power modules are single-output isolated DC/DC converters, housed in an industry standard quarter-brick package. These modules are rated up to 100W with a maximum load current of up to 30 A.

The PTQA series operates from a standard 48-V telecom central office (CO) supply and occupies only 3.3 in² of PCB area. The modules offer OEMs a compact and flexible high-output power source in an industry standard footprint. They are suitable for distributed power applications in both telecom and computing environments, and may be used for powering high-end microprocessors, DSPs, general purpose logic and analog.

Features include a remote On/Off control with optional logic polarity, an undervoltage lockout (UVLO), a differential remote sense, and an industry standard output voltage adjustment using an external resistor. Protection features include output overcurrent protection (OCP), overvoltage protection (OVP), and thermal shutdown (OTP).

The modules are fully integrated for stand-alone operation, and require no additional components.

STANDARD APPLICATION





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SLTS261C -MAY 2006-REVISED SEPTEMBER 2009

www.ti.com



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ORDERING INFORMATION

For the most current package and ordering information, see the Package Option Addendum at the end of this datasheet, or see the TI website at www.ti.com.

Table 1. PART NUMBERING SCHEME

	Input Voltage	Output Current	Output Voltage	Enable	Electrical Options		Pin Style
PTQA	4	30	033	N	2	Α	D
	4 = 48 V	30 = 30A	025 = 2.5 V	N = Negative	2 = V _O Adjust		D = Through-hole, Pb-free
		20 = 20A	033 = 3.3 V	P = Positive			S = SMD, SnPb solder ball
			050 = 5.0 V				Z = SMD, SnAgCu solder ball

ABSOLUTE MAXIMUM RATING

				UNIT
T _A	Operating Temperature Range	Over V _I Range		-40°C to 85°C ⁽¹⁾
$V_{I,}$	Maximum lanut Valtana	Continuous voltage		80 V
MAX	Maximum Input Voltage	Peak voltage for 100 ms duration	100 V	
			PTQA420050x2	400 W
P _O ,	Maximum Output Power		100 W	
MAX			75 W	
T _S	Storage Temperature			-40°C to 125°C
	Machaniaal Charle	Per Mil-STD-883, Method 2002.3 1 ms, 1/2	AD Suffix	250 G
	Mechanical Shock	Sine, mounted	AS or AZ Suffix	175 G
	Machaniaal Vibraniaa	Per Mil-STD-883, Method 2007.2 20-2000 Hz,	AD Suffix	15 G
	Mechanical Vibrarion	PCB mounted	AS or AZ Suffix	2.5 G
	Weight			30 grams
	Flammability	Meets UL 94V-O		

(1) See SOA curves or consult factory for appropriate derating.

Submit Documentation Feedback

Copyright © 2006–2009, Texas Instruments Incorporated



www.ti.com

SLTS261C -MAY 2006-REVISED SEPTEMBER 2009

ELECTRICAL CHARACTERISTICS PTQA430025

(Unless otherwise stated, T_A =25°C, V_I = 48 V, V_O = 2.5 V, C_O = 0 μF , and I_O = I_O max)

	DADAMETED	TEST CO	ONDITIONS				
	PARAMETER	IESI CC	ONDITIONS	MIN	TYP	MAX	UNIT
Io	Output Current	Over V _I range		0		30	Α
VI	Input Voltage Range	Over I _O Range		36	48	75	V
V _O tol	Set Point Voltage Tolerance				±1 ⁽¹⁾		%V _O
Reg _{temp}	Temperature Variation	-40°C >T _A > 85°C			±1.15		%V _O
Reg _{line}	Line Regulation	Over V _I range			±5		mV
Reg _{load}	Load Regulation	Over I _O range			±5		mV
ΔV_{o} tot	Total Output Voltage Variation	Includes set-point, line, load, -4	40°C >T _A > 85°C		±1.5	±3	%V _O
ΔV_{ADJ}	Output Adjust Range	P _O ≤ 75 W		-20		10	%V _O
η	Efficiency	I _O = 50% I _O max			91%		
V_R	V _O Ripple (pk-pk)	20 MHz bandwidth			50	100	mV_{pp}
t _{tr}	Transient Danness	0.1 A/µs slew rate, 50% to 75%	l _O max		150		μs
ΔV_{tr}	Transient Response	V _O over/undershoot			25		mV
I _{TRIP}	Overcurrent Threshold	Shutdown, followed by auto-rec	covery		41		Α
OVP	Output Overvoltage Protection	Output shutdown and latch off		120		%V _O	
OTP	Over Temperature Protection	Temperature Measurement at the nominal.		105		° C	
f_s	Switching Frequency	Over V _I range			300		kHz
UVLO	Lindon (oltografication)	V _{OFF}	V_I decreasing, $I_O = 6$ A		32.5		V
UVLO	Undervoltage Lockout	V _{HYS}	Hysteresis		1.5		V
On/Off In	nput: Negative Enable						
V_{IH}	Input High Voltage	Deferenced to \/		2.4		Open ⁽²⁾	V
V_{IL}	Input Low Voltage	Referenced to -V _I		-0.2		0.8	V
I _{IL}	Input Low Current				-0.3		mA
On/Off In	nput: Positive Enable						
V_{IH}	Input High Voltage	Deferenced to V		4.5		Open ⁽²⁾	V
V_{IL}	Input Low Voltage	Referenced to -V _I		-0.2		0.8	V
$I_{\rm IL}$	Input Low Current				-0.5		mA
I _{ISB}	Standby Input Current	Output disabled (pin 2 status se	et to Off)		37		mA
C _I	External Input Capacitance	Between +V _I and -V _I			100		μF
Co	External Output Capacitance	Between +V _O and -V _O		0		30000	μF
	Isolation Voltage	Input-to-output and input-to-cas	se	1500			Vdc
	Isolation Capacitance	Input-to-output			1200		pF
	Isolation Resistance	Input-to-output		10			МΩ

 ⁽¹⁾ If Sense(-) is not used, pin 5 must be connected to pin 4 for optimum output voltage accuracy.
 (2) The Remote On/Off input has an internal pull-up and may be controlled with an open collector (drain) interface. An open circuit correlates to a logic high. Consult the application notes for interface considerations.

NSTRUMENTS

SLTS261C -MAY 2006-REVISED SEPTEMBER 2009

www.ti.com

ELECTRICAL CHARACTERISTICS PTQA430033

(Unless otherwise stated, T_A =25°C, V_I = 48 V, V_O = 3.3 V, C_O = 0 μF , and I_O = I_O max)

	DADAMETED	TEST OF	ONDITIONS		PTQA	430033	
	PARAMETER	IESI CC	ONDITIONS	MIN	TYP	MAX	UNIT
Io	Output Current	Over V _I range		0		30	Α
VI	Input Voltage Range	Over I _O Range		36	48	75	V
V _O tol	Set Point Voltage Tolerance				±1 ⁽¹⁾		%V _O
Reg _{temp}	Temperature Variation	-40°C >T _A > 85°C			±1.15		%V _O
Reg _{line}	Line Regulation	Over V _I range			±5		mV
Reg _{load}	Load Regulation	Over I _O range			±5		mV
ΔV _o tot	Total Output Voltage Variation	Includes set-point, line, load, -4	40°C >T _A > 85°C		±1.5	±3	%V _O
ΔV_{ADJ}	Output Adjust Range	P _O ≤ 100 W		-20		10	%Vo
η	Efficiency	I _O = 50% I _O max			92%		
V_R	V _O Ripple (pk-pk)	20 MHz bandwidth			50	100	mV_{pp}
t _{tr}	Transient Danners	0.1 A/µs slew rate, 50% to 75%	I _O max		150		μs
ΔV_{tr}	Transient Response	V _O over/undershoot			33		mV
I _{TRIP}	Overcurrent Threshold	Shutdown, followed by auto-rec	covery		41		Α
OVP	Output Overvoltage Protection	Output shutdown and latch off		120		%V _O	
OTP	Over Temperature Protection	Temperature Measurement at the nominal.		105		°C	
f_s	Switching Frequency	Over V _I range			300		kHz
UVLO	Lindom rolto ao Lookovit	V _{OFF}	V _I decreasing, I _O = 6 A		32.5		V
0 VLO	Undervoltage Lockout	V _{HYS}	Hysteresis		1.5		v
On/Off Ir	nput: Negative Enable						
V_{IH}	Input High Voltage	Referenced to -V _I		2.4		Open ⁽²⁾	V
V_{IL}	Input Low Voltage	Neierenced to -v		-0.2		0.8	v
I _{IL}	Input Low Current				-0.3		mA
On/Off Ir	nput: Positive Enable						
V_{IH}	Input High Voltage	Potoropood to V		4.5		Open ⁽²⁾	V
V_{IL}	Input Low Voltage	Referenced to -V _I		-0.2		0.8	v
I_{IL}	Input Low Current				-0.5		mA
I _{Isb}	Standby Input Current	Output disabled (pin 2 status se	et to Off)		42		mA
C _I	External Input Capacitance	Between +V _I and -V _I			100		μF
C _O	External Output Capacitance	Between +V _O and -V _O		0		30000	μF
	Isolation Voltage	Input-to-output and input-to-cas	se	1500			Vdc
	Isolation Capacitance	Input-to-output			1200		pF
	Isolation Resistance	Input-to-output		10			ΜΩ

Submit Documentation Feedback

 ⁽¹⁾ If Sense(-) is not used, pin 5 must be connected to pin 4 for optimum output voltage accuracy.
 (2) The Remote On/Off input has an internal pull-up and may be controlled with an open collector (drain) interface. An open circuit correlates to a logic high. Consult the application notes for interface considerations.



www.ti.com

SLTS261C -MAY 2006-REVISED SEPTEMBER 2009

ELECTRICAL CHARACTERISTICS PTQA420050

(Unless otherwise stated, T_A =25°C, V_I = 48 V, V_O = 5.0 V, C_O = 0 μF , and I_O = I_O max)

	PARAMETER	TEST CO	ONDITIONS		PTQA	420050			
	FARAIVIE I EK	151 00	פאטוווטאט	MIN	TYP	MAX	UNIT		
Io	Output Current	Over V _I range		0		20	Α		
VI	Input Voltage Range	Over I _O Range		36	48	75	V		
V _O tol	Set Point Voltage Tolerance				±1 ⁽¹⁾		%V _O		
Reg _{temp}	Temperature Variation	-40°C >T _A > 85°C			±1.15		%V _O		
Reg _{line}	Line Regulation	Over V _I range			±5		mV		
Reg _{load}	Load Regulation	Over I _O range			±5		mV		
ΔV_{o} tot	Total Output Voltage Variation	Includes set-point, line, load, -4	40°C >T _A > 85°C		±1.5	±3	%V _O		
ΔV_{ADJ}	Output Adjust Range	P _O ≤ 100 W		10	%V _O				
η	Efficiency	I _O = 50% I _O max			92.5%				
V_R	V _O Ripple (pk-pk)	20 MHz bandwidth			50	100	mV_{pp}		
t _{tr}	Transient Despense	0.1 A/µs slew rate, 50% to 75%	o I _O max		50 100 r 100 50 29 120				
ΔV_{tr}	Transient Response	V _O over/undershoot			50		mV		
I _{TRIP}	Overcurrent Threshold	Shutdown, followed by auto-red		29		Α			
OVP	Output Overvoltage Protection	Output shutdown and latch off		120		%V _O			
OTP	Over Temperature Protection	Temperature Measurement at t nominal.		105		° C			
fs	Switching Frequency	Over V _I range			300		kHz		
111/1/0	l la deminita de la calcació	V _{OFF}	V _I decreasing, I _O = 6 A		32.5		\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \		
UVLO	Undervoltage Lockout	V _{HYS}	Hysteresis		1.5		V		
On/Off Ir	nput: Negative Enable								
V_{IH}	Input High Voltage	Deferenced to \/		2.4		Open ⁽²⁾	V		
V_{IL}	Input Low Voltage	Referenced to -V _I		-0.2		0.8	V		
I _{IL}	Input Low Current				-0.3		mA		
On/Off Ir	nput: Positive Enable								
V_{IH}	Input High Voltage	Defended to V		4.5		Open ⁽²⁾	V		
V_{IL}	Input Low Voltage	Referenced to -V _I		-0.2		0.8	V		
$I_{\rm IL}$	Input Low Current				-0.5		mA		
I _{Isb}	Standby Input Current	Output disabled (pin 2 status se	et to Off)		58		mA		
C _I	External Input Capacitance	Output disabled (pin 2 status set to Off) 58 e Between +V _I and -V _I 100							
Co	External Output Capacitance	Between +V _O and -V _O		0		30000	μF		
	Isolation Voltage	Input-to-output and input-to-cas	se	1500			Vdc		
	Isolation Capacitance	Input-to-output			1200		pF		
	Isolation Resistance	Input-to-output		10			ΜΩ		

⁽¹⁾ If Sense(-) is not used, pin 5 must be connected to pin 4 for optimum output voltage accuracy.

⁽²⁾ The Remote On/Off input has an internal pull-up and may be controlled with an open collector (drain) interface. An open circuit correlates to a logic high. Consult the application notes for interface considerations.

SLTS261C -MAY 2006-REVISED SEPTEMBER 2009

www.ti.com

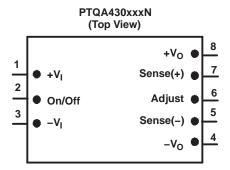
INSTRUMENTS

PIN DESCRIPTIONS

- + V_i : The positive input for the module with respect to $-V_i$. When powering the module from a -48-V telecom central office supply, this input is connected to the primary system ground.
- -V_i: The negative input supply for the module, and the 0 VDC reference for the Remote On/Off input. When powering the module from a +48-V supply, this input is connected to the 48-V return.

Remote On/Off: This input controls the On/Off status of the output voltage. It is either driven low $(-V_1)$ potential, or left open-circuit. For units identified with the NEN option, applying a logic low to this pin will enable the output. And for units identified with the PEN option, the output will be disabled.

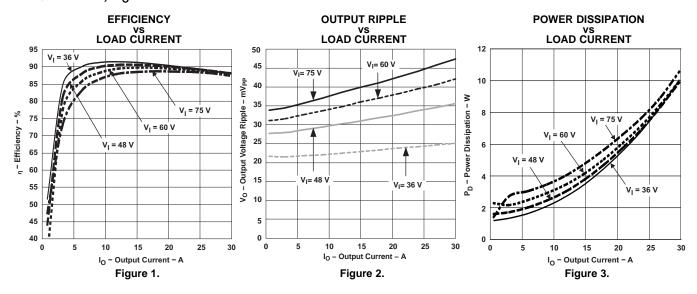
- V_0 Adjust: Allows the output voltage to be trimmed by up or down between +10% and -20% of its nominal value. The adjustment method uses a single external resistor. Connecting the resistor between V_0 Adjust and $-V_0$ adjusts the output voltage lower, and placing it between V_0 Adjust and $+V_0$ adjusts the output higher. The calculations for the resistance value follows industry standard formulas. For further information consult the application note on output voltage adustment.
- **+V_O:** The positive power output with respect to $-V_O$, which is DC isolated from the input supply pins. If a negative output voltage is desired, $+V_O$ should be connected to the secondary circuit common and the output taken from $-V_O$.
- $-\mathbf{V}_{O}$: The negative power output with respect to $+\mathbf{V}_{O}$, which is DC isolated from the input supply pins. This output is normally connected to the secondary circuit common when a positive output voltage is desired.
- **Sense(+):** Provides the converter with an output sense capability to regulate the set-point voltage directly at the load. When used with Sense(-), the regulation circuitry will compensate for voltage drop between the converter and the load. The pin may be left open circuit, but connecting it to +V_O improves load regulation.
- **Sense(–):** Provides the converter with an output sense capability when used in conjunction with Sense(+) input. For optimum output voltage accuracy this pin should always be connected to $-V_0$.



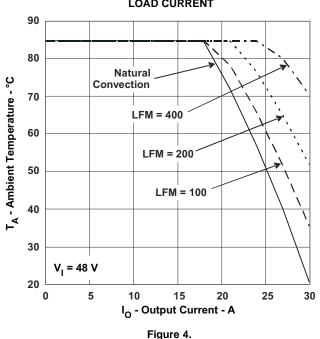


TYPICAL CHARACTERISTICS

PTQA430025, $V_0 = 2.5 V^{(1)}$ (2)



AMBIENT TEMPERATURE VS LOAD CURRENT



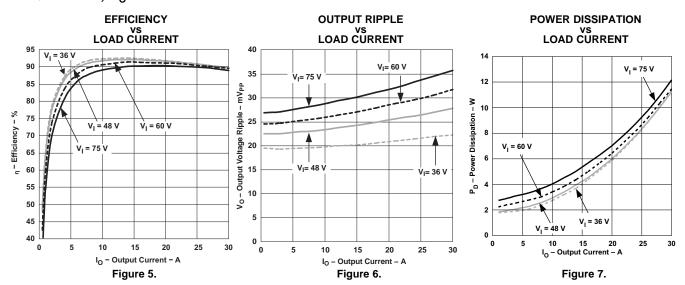
- (1) All data listed in Figure 1, Figure 2, and Figure 3 have been developed from actual products tested at 25°C. This data is considered typical data for the dc-dc converter.
- (2) The temperature derating curves represent operating conditions at which internal components are at or below manufacturer's maximum rated operating temperature. Derating limits apply to modules soldered directly to a 100–mm x 100–mm, double-sided PCB with 2 oz. copper. For surface mount packages, multiple vias (plated through holes) are required to add thermal paths around the power pins. Please refer to the mechanical specification for more information. Applies to Figure 4.

SLTS261C -MAY 2006-REVISED SEPTEMBER 2009

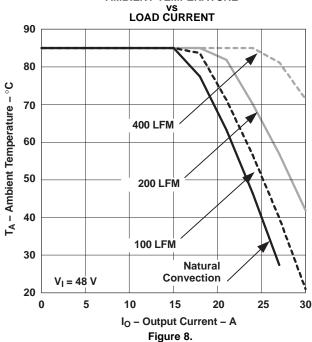


TYPICAL CHARACTERISTICS

PTQA430033, $V_0 = 3.3 V^{(1)}$ (2)



AMBIENT TEMPERATURE



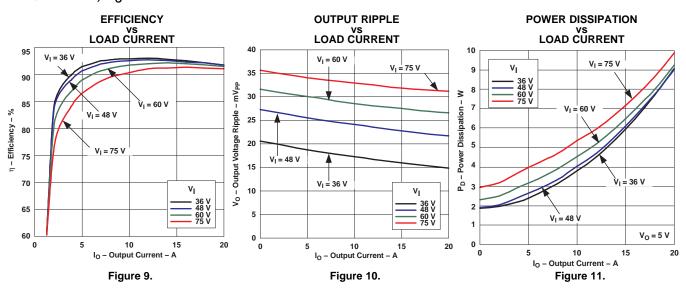
- (1) All data listed in Figure 5, Figure 6, and Figure 7 have been developed from actual products tested at 25°C. This data is considered typical data for the dc-dc converter.
- (2) The temperature derating curves represent operating conditions at which internal components are at or below manufacturer's maximum rated operating temperature. Derating limits apply to modules soldered directly to a 100–mm × 100–mm, double-sided PCB with 2 oz. copper. For surface mount packages, multiple vias (plated through holes) are required to add thermal paths around the power pins. Please refer to the mechanical specification for more information. Applies to Figure 8.

www.ti.com

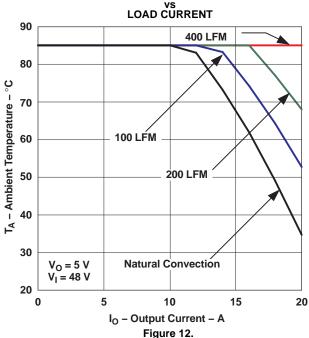
SLTS261C -MAY 2006-REVISED SEPTEMBER 2009

TYPICAL CHARACTERISTICS

PTQA420050, $V_0 = 5.0 V^{(1)}$ (2)



AMBIENT TEMPERATURE



- (1) All data listed in Figure 9, Figure 10, and Figure 11 have been developed from actual products tested at 25°C. This data is considered typical data for the dc-dc converter.
- (2) The temperature derating curves represent operating conditions at which internal components are at or below manufacturer's maximum rated operating temperature. Derating limits apply to modules soldered directly to a 100–mm x 100–mm, double-sided PCB with 2 oz. copper. For surface mount packages, multiple vias (plated through holes) are required to add thermal paths around the power pins. Please refer to the mechanical specification for more information. Applies to Figure 12.

SLTS261C -MAY 2006-REVISED SEPTEMBER 2009

www.ti.com

APPLICATION INFORMATION

Operating Features and System Considerations for the PTQA Series of DC/DC Converters

Overcurrent Protection

To protect against load faults, these converters incorporate output overcurrent protection. Applying a load to the output that exceeds the converter's overcurrent threshold (see applicable specification) will cause the output voltage to momentarily fold back, and then shut down. Following shutdown the module will periodically attempt to automatically recover by initiating a soft-start power-up. This is often described as a hiccup mode of operation, whereby the module continues in the cycle of successive shutdown and power up until the load fault is removed. Once the fault is removed, the converter automatically recovers and returns to normal operation.

Output Overvoltage Protection

Each converter incorporates protection circuitry that continually senses for an output overvoltage (OV) condition. The OV threshold is set approximately 20% higher than the nominal output voltage. If the converter output voltage exceeds this threshold, the converter is immediately shut down and remains in a latched-off state. To resume normal operation the converter must be actively reset. This can only be done by momentarily removing the input power to the converter. For fail-safe operation and redundancy, the OV protection uses circuitry that is independent of the converter's internal feedback loop.

Overtemperature Protection

Overtemperature protection is provided by an internal temperature sensor, which closely monitors the temperature of the converter's printed circuit board (PCB). If the sensor exceeds a temperature of approximately 105°C, the converter will shut down. The converter will then automatically restart when the sensed temperature drops back to approximately 95°C. When operated outside its recommended thermal derating envelope (see data sheet SOA curves), the converter will typically cycle on and off at intervals from a few seconds to one or two minutes. This is to ensure that the internal components are not permanently damaged from excessive thermal stress.

Undervoltage Lockout

The Undervoltage lockout (UVLO) is designed to prevent the operation of the converter until the input voltage is at the minimum input voltage. This prevents high start-up current during normal power-up of the converter, and minimizes the current drain from the input source during low input voltage conditions. The UVLO circuitry also overrides the operation of the Remote On/Off control.

Primary-Secondary Isolation

These converters incorporate electrical isolation between the input terminals (primary) and the output terminals (secondary). All converters are production tested to a withstand voltage of 1500 VDC. This specification complies with UL60950 and EN60950 requirements. This allows the converter to be configured for either a positive or negative input voltage source. The data sheet Pin Descriptions section provides guidance as to the correct reference that must be used for the external control signals.

Input Current Limiting

The converter is not internally fused. For safety and overall system protection, the maximum input current to the converter must be limited. Active or passive current limiting can be used. Passive current limiting can be a fast acting fuse. A 125-V fuse, rated no more than 10 A, is recommended. Active current limiting can be implemented with a current limited *Hot-Swap* controller.

Thermal Considerations

Airflow may be necessary to ensure that the module can supply the desired load current in environments with elevated ambient temperatures. The required airflow rate may be determined from the Safe Operating Area (SOA) thermal derating chart (see typical characteristics).

Submit Documentation Feedback

Not Recommended for New Designs



PTQA430025, PTQA430033, PTQA420050

www.ti.com

SLTS261C -MAY 2006-REVISED SEPTEMBER 2009

Differential Remote Sense

The remote sense pins allows the converter to precisely regulate the DC output voltage at a remote location. This might be a power plane on an inner layer of the host PCB. Connecting Sense(+) directly to $+V_O$, and Sense(-) to $-V_O$ will improve output voltage accuracy. In the event that the sense pins are left open-circuit, an internal $10-\Omega$ resistor between each sense pin and its corresponding output prevents an excessive rise in the output voltage. For practical reasons, the amount of IR voltage compensation should be limited to 0.5 V maximum.

The remote sense feature is designed to compensate for limited amounts of *IR* voltage drop. It is **not** intended to compensate for the forward drop of a non-linear or frequency dependent components that may be placed in series with the converter output. Examples of such components include OR-ing diodes, filter inductors, ferrite beads, and fuses. Enclosing these components with the remote sense connections effectively places them inside the regulation control loop, which can affect the stability of the regulator.

SLTS261C -MAY 2006-REVISED SEPTEMBER 2009

www.ti.com

Using the Remote On/Off Function on the PTQA Series of DC/DC Converters

For applications requiring output voltage On/Off control, the PTQA series of DC/DC converters incorporate a *Remote On/Off* control (pin 2). This feature can be used to switch the module off without removing the applied input source voltage. When placed in the *Off* state, the standby current drawn from the input source is typically reduced to 3 mA.

Negative Output Enable (NEN)

Models using the negative enable option, the *Remote On/Off* (pin 2) control must be driven to a logic low voltage for the converter to produce an output. This is accomplished by either permanently connecting pin 2 to $-V_1$ (pin 3), or driving it low with an external control signal. Table 2 shows the input requirements of pin 2 for those modules with the *NEN* option.

Table 2. On/Off Control Requirements for Negative Enable

	PARAMETER	MIN	TYP	MAX
V_{IH}	Disable	2.4 V		20 V
V_{IL}	Enable	-0.2 V		0.8 V
V _{o/c}	Open-Circuit		9 V	15 V
I_{\parallel}	Pin 2 at -V ₁			−0.75 mA

Positive Output Enable (PEN)

For those models with the positive enable (PEN) option, leaving pin 2 open circuit, (or driving it to an equivalent logic high voltage), will enable the converter output. This allows the module to produce an output voltage whenever a valid input source voltage is applied to $+V_1$ with respect to $-V_1$. If a logic-low signal is then applied to pin 2 the converter output is disabled. Table 3 gives the input requirements of pin 2 for modules with the *PEN* option.

Table 3. On/Off Control Requirements for Positive Enable

	PARAMETER	MIN	TYP	MAX
V_{IH}	Enable	4.5 V		20 V
V_{IL}	Disable	-0.2 V		0.8 V
V _{o/c}	Open-Circuit		5 V	7 V
I	Pin 2 at –V _I			–0.5 mA

Notes:

- 1. The Remote On/Off control uses $-V_1$ (pin 3) as its ground reference. All voltages are with respect to $-V_1$.
- 2. An open-collector device (preferably a discrete transistor) is recommended. A pull-up resistor is not required. If one is added the pull-up voltage should not exceed 20 V.

Caution: Do not use a pull-resistor to $+V_1$ (pin 1). The remote On/Off control has a maximum input voltage of 20 V. Exceeding this voltage will overstress, and possibly damage, the converter.

- 3. The *Remote On/Off* pin may be controlled with devices that have a totem-pole output. This is provided the output high level voltage (V_{OH}) meets the module's minimum V_{IH} specified in Table 2. If a TTL gate is used, a pull-up resistor may be required to the logic supply voltage.
- 4. The converter incorporates an *undervoltage lockout* (UVLO). The UVLO keeps the converter off until the input voltage is close to the minimum specified operating voltage. This is regardless of the state of the *Remote On/Off* control. Consult the product specification for the UVLO input voltage thresholds.

2 Submit Documentation Feedback

www.ti.com

SLTS261C -MAY 2006-REVISED SEPTEMBER 2009

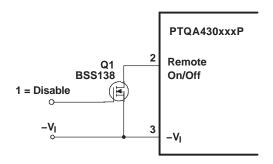


Figure 13. Recommended Control or Remote On/Off Input

Turn-On: With a valid input source voltage applied, the converter produces a regulated output voltage within 75 ms of the output being enabled. Figure 14 shows the output response of the PTQA430033P following the removal of the logic-low signal from the *Remote On/Off* (pin 2); see Figure 13. This corresponds to the drop in Q1 V_{GS} in Figure 14. Although the rise-time of the output voltage is short (<10 ms), the indicated delay time will vary depending upon the input voltage and the module's internal timing. The waveforms were measured with 48 VDC input voltage, and a 10-A resistive load.

Turn-Off Time: When a valid input source is removed or if the *Remote On/Off* (pin 2) is used to disable the output, with no external output capacitance, the module powers down within 200 μs. Figure 15 shows that, during power down, there is a small undershoot, typically less than 300 mV (or less than a diode drop). If used to supply processor I/O voltages, the low undershoot ensures the parasitic diodes do not conduct current and potentially cause damage to external circuitry.

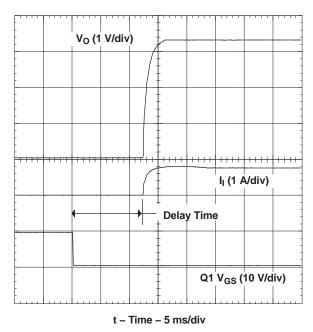


Figure 14. Power Up

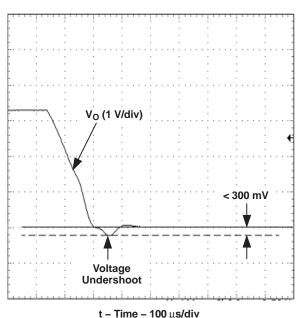


Figure 15. Power Down

SLTS261C - MAY 2006-REVISED SEPTEMBER 2009



Adjusting the Output Voltage of the 100-W Rated PTQA Series of Isolated DC/DC Converters

The output voltage adjustment of the PTQA series of isolated DC/DC converters follows the standard adopted by popular 1/4-brick DC/DC converters. Adjustment is accomplished with a single external resistor that can adjust the output voltage from –20% to +10% of the nominal set-point voltage. The placement of the resistor determines the direction of adjustment, up or down, and the value of the magnitude of adjustment.

Adjust Up: To increase the output voltage add a resistor, R1, between V_0 Adjust (pin 6) and Sense(+) (pin 7).

Adjust Down: Add a resistor, (R2), between V_O Adjust (pin 6) and Sense(–) (pin 5).

Refer to Figure 16 for the placement of the required resistor, R1 or (R2).

The values of R1 [adjust up], and (R2) [adjust down], can be calculated using the following formulas or selected from Table 4.

$$R1 = \frac{5.11 \text{ V}_{\text{O}} (100 + \Delta\%)}{1.225 \Delta\%} - \frac{511}{\Delta\%} - 10.22 \text{ (k}\Omega)$$
(1)

$$(R2) = 5.11 \frac{100}{\Delta\%} - 10.22 \quad (k\Omega)$$
 (2)

Where:

 Δ % = Amount of adjustment in %

V_O = Original set-point voltage

Notes:

- 1. Use only a single 1% resistor in either the R1 or (R2) location. Place the resistor as close to the converter as possible.
- 2. If the output voltage is increased, the maximum load current must be derated according to the following equation.

$$I_{O}(max) = \frac{V_{O} \times I_{O}(rated)}{V_{A}}$$
(3)

Where:

V_O = Original set-point voltage

V_A = Adjusted output voltage (measured between pins 8 and 4)

In any instance, the load current must not exceed the converter's maximum rated output current of 30 A.

3. The overvoltage threshold is fixed, and is set approximately 20% above the nominal output voltage. Adjusting the output voltage higher reduces the voltage margin between the adjusted output voltage and the overvoltage (OV) protection threshold. This could make the module sensitive to OV fault detection, as a result of random noise and load transients.

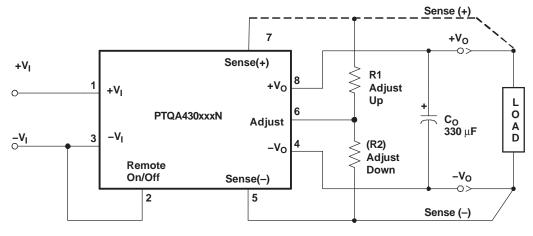


Figure 16.



www.ti.com

SLTS261C -MAY 2006-REVISED SEPTEMBER 2009

Table 4. Standard Adjustment Resistor Values

	Adjust	ted Output Volta	age (V)		Trim-Up R _{AD}	J	Tı	rim-Down R	\DJ
V _O (nom) % Adjust (V)	5.0 V	3.3 V	2.5 V	5.0 V R1 (kΩ)	3.3 V R1 (kΩ)	2.5 V R1 (kΩ)	5.0 V R2 (kΩ)	3.3 V R2 (kΩ)	2.5 V R2 (kΩ)
+10	5.50	3.630	2.750	169	90.9	53.6	-	-	-
+ 9	5.45	3.597	2.725	187	100	59.0	-	-	-
+ 8	5.40	3.564	2.700	205	113	66.5	-	-	-
+ 7	5.35	3.531	2.675	237	127	76.8	-	-	-
+ 6	5.30	3.498	2.650	274	147	88.7	-	-	-
+ 5	5.25	3.465	2.625	324	178	107	-	-	-
+ 4	5.20	3.432	2.600	402	221	133	-	-	-
+ 3	5.15	3.399	2.575	536	294	178	-	-	-
+ 2	5.10	3.366	2.550	787	432	267	-	-	-
+ 1	5.05	3.333	2.525	1580	866	536	-	-	-
0	5.00	3.300	2.500	Open	Open	Open	-	-	-
-1	4.95	3.267	2.475	-	-	-	499	499	499
-2	4.90	3.234	2.450	-	-	-	243	243	243
-3	4.85	3.201	2.425	-	-	-	158	158	158
-4	4.80	3.168	2.400	-	-	-	118	118	118
-5	4.75	3.135	2.375	-	-	-	90.9	90.9	90.9
-6	4.70	3.102	2.350	-	-	-	75	75	75
-7	4.65	3.069	2.325	-	-	-	63.4	63.4	63.4
-8	4.60	3.036	2.300	-	-	-	53.6	53.6	53.6
-9	4.55	3.003	2.275	-	-	-	46.4	46.4	46.4
-10	4.50	2.970	2.250	-	-	-	41.2	41.2	41.2
-11	4.45	2.937	2.225	-	-	-	36.5	36.5	36.5
-12	4.40	2.904	2.200	-	-	-	32.4	32.4	32.4
-13	4.35	2.871	2.175	-	-	-	28.7	28.7	28.7
-14	4.30	2.838	2.150	-	-	-	26.1	26.1	26.1
-15	4.25	2.805	2.125	-	-	-	23.7	23.7	23.7
-16	4.20	2.772	2.100	-	-	-	21.5	21.5	21.5
-17	4.15	2.739	2.075	-	-	-	19.6	19.6	19.6
-18	4.10	2.706	2.050	-	-	-	18.2	18.2	18.2
-19	4.05	2.673	2.025	-	-	-	16.5	16.5	16.5
-20	4.00	2.640	2.000	-	-	-	15.4	15.4	15.4

Copyright © 2006–2009, Texas Instruments Incorporated

Submit Documentation Feedback





27-Apr-2017

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
PTQA420050N2AD	NRND	Through- Hole Module	EAP	8	9	RoHS (In Work) & Green (In Work)	SN	N / A for Pkg Type	-40 to 85		
PTQA420050N2AS	NRND	Surface Mount Module	EAQ	8	9	RoHS (In Work) & Green (In Work)	SNPB	Level-1-235C-UNLIM/ Level-3-260C-168HRS	-40 to 85		
PTQA420050N2AZ	NRND	Surface Mount Module	BAQ	8	9	RoHS (In Work) & Green (In Work)	SNAGCU	Level-3-260C-168 HR	-40 to 85		
PTQA420050P2AD	NRND	Through- Hole Module	EAP	8	9	RoHS (In Work) & Green (In Work)	SN	N / A for Pkg Type	-40 to 85		
PTQA420050P2AS	NRND	Surface Mount Module	EAQ	8	9	RoHS (In Work) & Green (In Work)	SNPB	Level-1-235C-UNLIM/ Level-3-260C-168HRS	-40 to 85		
PTQA420050P2AZ	NRND	Surface Mount Module	BAQ	8	9	RoHS (In Work) & Green (In Work)	SNAGCU	Level-3-260C-168 HR	-40 to 85		
PTQA430025P2AD	NRND	Through- Hole Module	EAP	8	9	RoHS (In Work) & Green (In Work)	SN	N / A for Pkg Type	-40 to 85		
PTQA430033N2AD	NRND	Through- Hole Module	EAP	8	9	RoHS (In Work) & Green (In Work)	SN	N / A for Pkg Type	-40 to 85		

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".



PACKAGE OPTION ADDENDUM

27-Apr-2017

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

DOUBLE SIDED MODULE BAQ (R-PDSS-B8) - 2.22 (56,39) 0.495 0.110 (12,57)2.000 (50,80) (2,79)MAX. Note J 0.43 (10,90)8 • Solder Ball 0.300 Ø0.040 (1,02) (7,62) 0.600 1.45 PX000000X 0.150 8 Places (36,83)• 0.600 (15,24) — (3,81) 4 Places See Note I. xxx **₹** • DATE CODE **•** 3 4 • TOP VIEW SIDE VIEW 2.260 (57,40) 0.130. - 2.000 (50,80) (3,30)Lowest Component 0.010 MIN. (0,25) 0.45 Bottom side (11,43)Clearance 0.300 (7,62) 0.600 0.150 (15,24) 1.490 — (3,81) 4 Places (37,85)Host Board Ø0.085 (2,16) 8 Places See Note F, G & H Note E -0.472 (12,00)PCB Layout

NOTES: Α. All linear dimensions are in inches (mm).

- This drawing is subject to change without notice.
- 2 place decimals are ± 0.020 ($\pm 0,51$ mm). 3 place decimals are ± 0.010 ($\pm 0,25$ mm).
- Recommended keep out area for user components.
- Power pin connection should utilize four or more vias to the interior power plane of 0.025 (0,63) I.D. per input, ground and output pin (or the electrical equivalent).
- G. Paste screen opening: 0.080 (2,03) to 0.085 (2,16). Paste screen thickness: 0.006 (0,15).

MAX.

- H. Pad type: Solder mask defined.
- I. All pins: Material Copper Alloy Finish Tin (100%) over Nickel plate Solder Ball 96.5 Sn/3.0 Ag/0.5 Cu

4207714/A 02/06

J. Dimension prior to reflow solder.



DOUBLE SIDED MODULE EAP (R-PDSS-T8) - 2.22 (56,39) -0.140 0.110 (3,55)2.000 (50,80) (2,79)Ø0.060 (1,52) 2 Places (10,90)Note F, G. 8 • 0.300 Ø0.040 (1,02) (7,62) 0.600 PXXXXXXX 0.150 1.45 -6 Places 0.600 15,24) • - (3,81) 4 Places (36,83)Note G, H. XXX T 0 DATE CODE **•** 3 40 Lowest Component(0,25) 0.010 MIN. Bottom side TOP VIEW Clearance Host Board 0.472 (12,00)MAX. 2.260 (57,40) SIDE VIEW 0.130 2.000 (50,80) (3,30)Note E -0.45 (11,43)8**0** 0.300 0.600 (7,62) 0 0.150 0 0 (15,24) 1.490 - (3,81) 4 Places (37,85)0 4**Q** Ø0.086 (2,20) Min. 2 Places Plated through hole. Ø0.055 (1,40) Min. 6 Places Plated through hole. 4207562/A 12/05 PCB Layout

- NOTES:
- A. All linear dimensions are in inches (mm).
- This drawing is subject to change without notice.
- C. 2 place decimals are ± 0.020 (± 0.51 mm).
- D. 3 place decimals are ± 0.010 (± 0.25 mm).
- E. Recommended keep out area for user components.
- Pins are 0.060" (1,52) diameter with 0.125" (3,20) diameter standoff shoulder.
- G. All pins: Material Copper Alloy
 Finish Tin (100%) over Nickel plate

 H. Pins are 0.040" (1,02) diameter with
 0.070" (1,78) diameter standoff shoulder.



EAQ (R-PDSS-B8) DOUBLE SIDED MODULE - 2.22 (56,39) 0.495 0.110 (12,57)- 2.000 (50,80) (2,79)MAX. Note J 0.43 (10,90)8 • Solder Ball 0.300 Ø0.040 (1,02) (7,62) 0.600 1.45 0.150 8 Places (36,83)• 0.600 (15,24) - (3,81) 4 Places See Note I. • **•** 3 4 • TOP VIEW SIDE VIEW 2.260 (57,40) 0.130. - 2.000 (50,80) (3,30)Lowest Component 0.010 MIN. (0,25) 0.45 Bottom side (11,43)Clearance 0.300 (7,62) 0.600 0.150 (15,24) 1.490 — (3,81) 4 Places (37,85)Host Board Ø0.085 (2,16) 8 Places See Note F, G & H Note E -0.472 (12,00)PCB Layout MAX. 4207563/A 12/05

NOTES: Α. All linear dimensions are in inches (mm).

- This drawing is subject to change without notice.
- 2 place decimals are ± 0.020 ($\pm 0,51$ mm). 3 place decimals are ± 0.010 ($\pm 0,25$ mm).
- Recommended keep out area for user components.
- Power pin connection should utilize four or more vias to the interior power plane of 0.025 (0,63) I.D. per input, ground and output pin (or the electrical equivalent).
- G. Paste screen opening: 0.080 (2,03) to 0.085 (2,16). Paste screen thickness: 0.006 (0,15).
- H. Pad type: Solder mask defined.
- I. All pins: Material Copper Alloy
 Finish Tin (100%) over Nickel plate
 Solder Ball See product data sheet.

J. Dimension prior to reflow solder.



IMPORTANT NOTICE

Texas Instruments Incorporated (TI) reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete.

TI's published terms of sale for semiconductor products (http://www.ti.com/sc/docs/stdterms.htm) apply to the sale of packaged integrated circuit products that TI has qualified and released to market. Additional terms may apply to the use or sale of other types of TI products and services.

Reproduction of significant portions of TI information in TI data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such reproduced documentation. Information of third parties may be subject to additional restrictions. Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyers and others who are developing systems that incorporate TI products (collectively, "Designers") understand and agree that Designers remain responsible for using their independent analysis, evaluation and judgment in designing their applications and that Designers have full and exclusive responsibility to assure the safety of Designers' applications and compliance of their applications (and of all TI products used in or for Designers' applications) with all applicable regulations, laws and other applicable requirements. Designer represents that, with respect to their applications, Designer has all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. Designer agrees that prior to using or distributing any applications that include TI products, Designer will thoroughly test such applications and the functionality of such TI products as used in such applications.

TI's provision of technical, application or other design advice, quality characterization, reliability data or other services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using TI Resources in any way, Designer (individually or, if Designer is acting on behalf of a company, Designer's company) agrees to use any particular TI Resource solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

Designer is authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY DESIGNER AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

Unless TI has explicitly designated an individual product as meeting the requirements of a particular industry standard (e.g., ISO/TS 16949 and ISO 26262), TI is not responsible for any failure to meet such industry standard requirements.

Where TI specifically promotes products as facilitating functional safety or as compliant with industry functional safety standards, such products are intended to help enable customers to design and create their own applications that meet applicable functional safety standards and requirements. Using products in an application does not by itself establish any safety features in the application. Designers must ensure compliance with safety-related requirements and standards applicable to their applications. Designer may not use any TI products in life-critical medical equipment unless authorized officers of the parties have executed a special contract specifically governing such use. Life-critical medical equipment is medical equipment where failure of such equipment would cause serious bodily injury or death (e.g., life support, pacemakers, defibrillators, heart pumps, neurostimulators, and implantables). Such equipment includes, without limitation, all medical devices identified by the U.S. Food and Drug Administration as Class III devices and equivalent classifications outside the U.S.

TI may expressly designate certain products as completing a particular qualification (e.g., Q100, Military Grade, or Enhanced Product). Designers agree that it has the necessary expertise to select the product with the appropriate qualification designation for their applications and that proper product selection is at Designers' own risk. Designers are solely responsible for compliance with all legal and regulatory requirements in connection with such selection.

Designer will fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of Designer's non-compliance with the terms and provisions of this Notice.